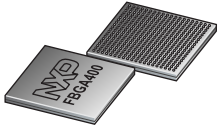


# SOT2130-1

LFBGA400, fine-pitch ball grid array, 400 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.63 mm body

26 June 2025

Package information



## 1 Package summary

Package type descriptive code	FBGA400
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	09-06-2025
Manufacturer package code	98ASA01736D

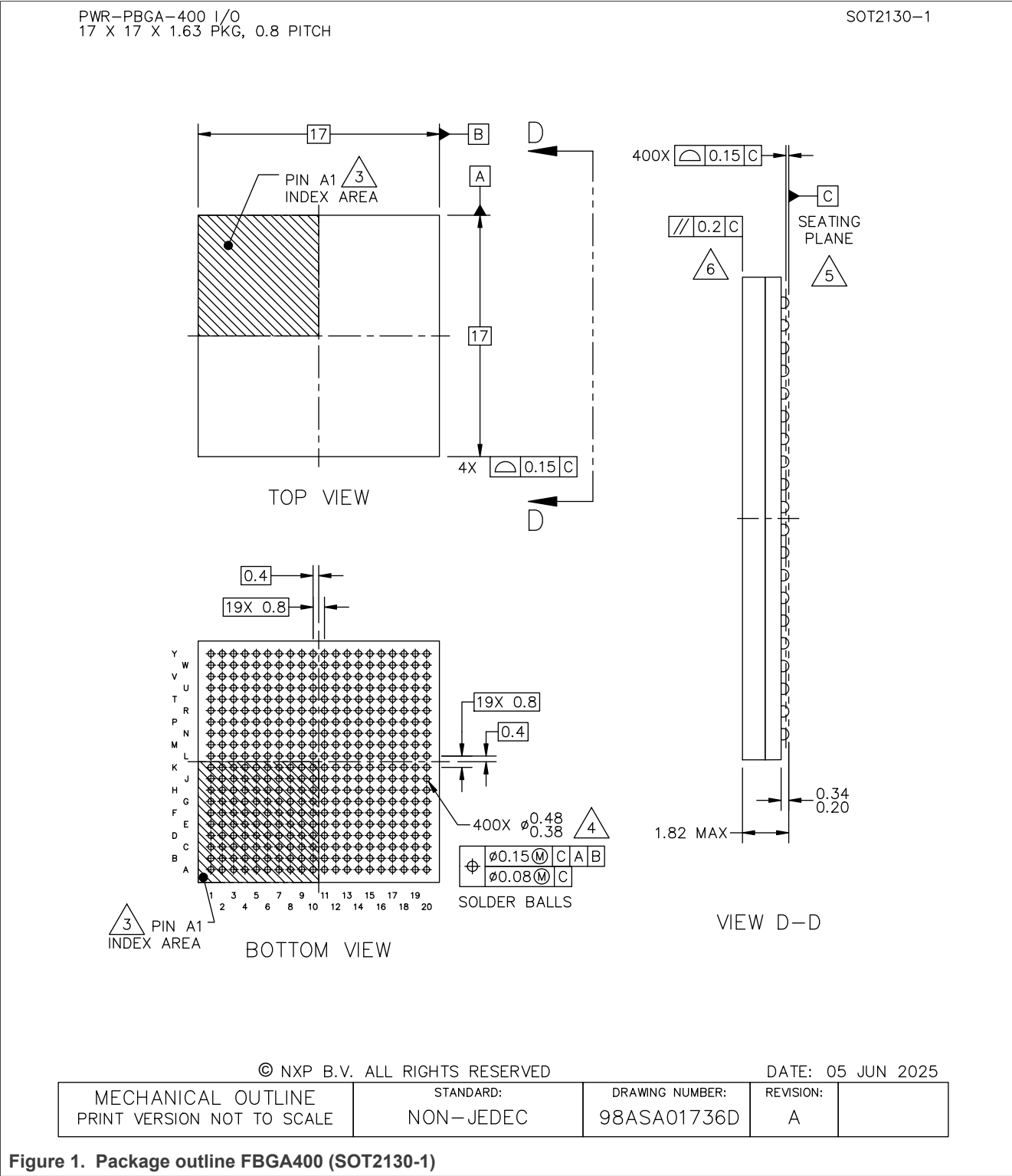
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
package height	1.45	1.63	1.82	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	400	-	



LFBGA400, fine-pitch ball grid array, 400 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.63 mm body

2 Package outline



LFBGA400, fine-pitch ball grid array, 400 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.63 mm body

3 Soldering

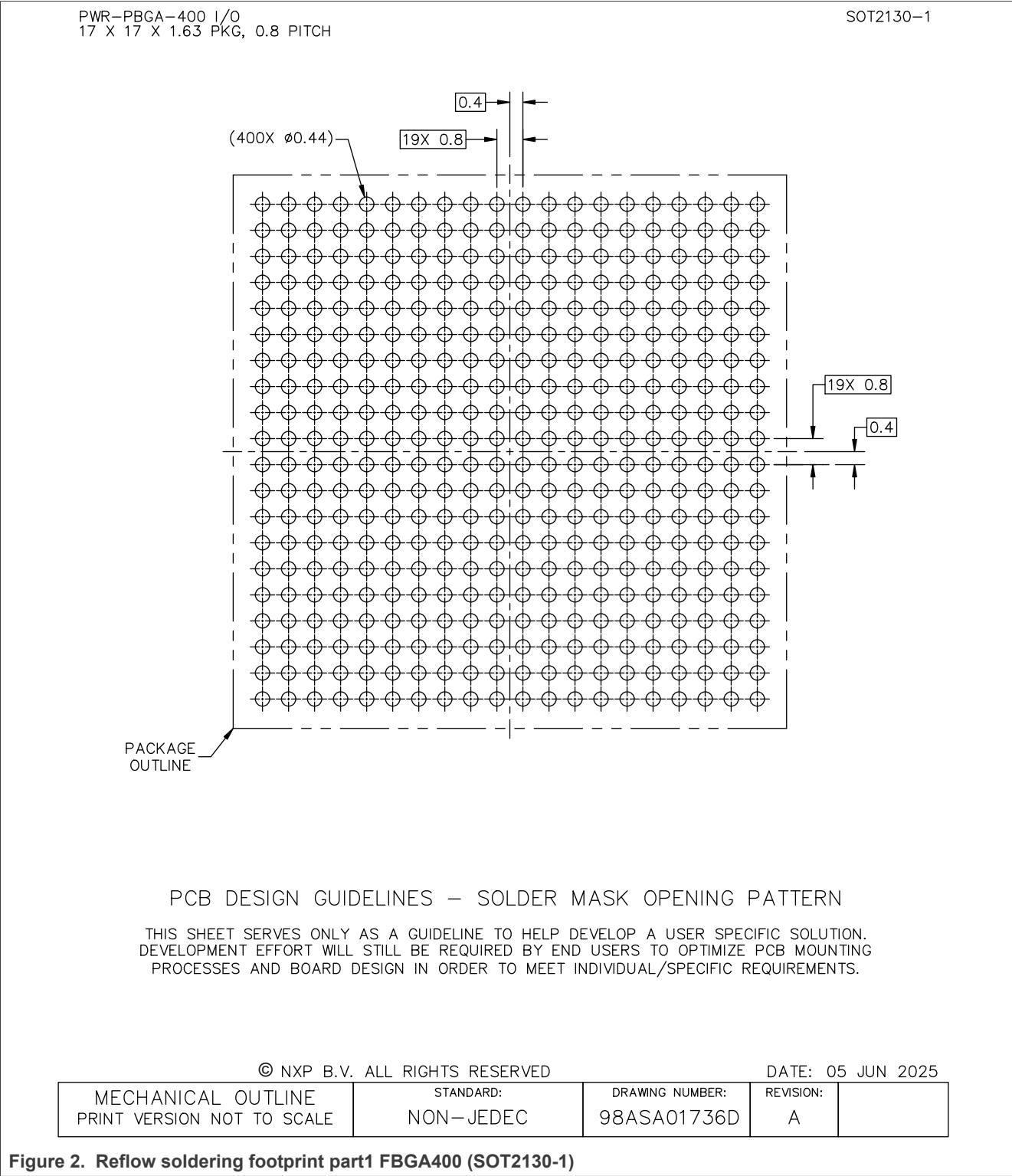
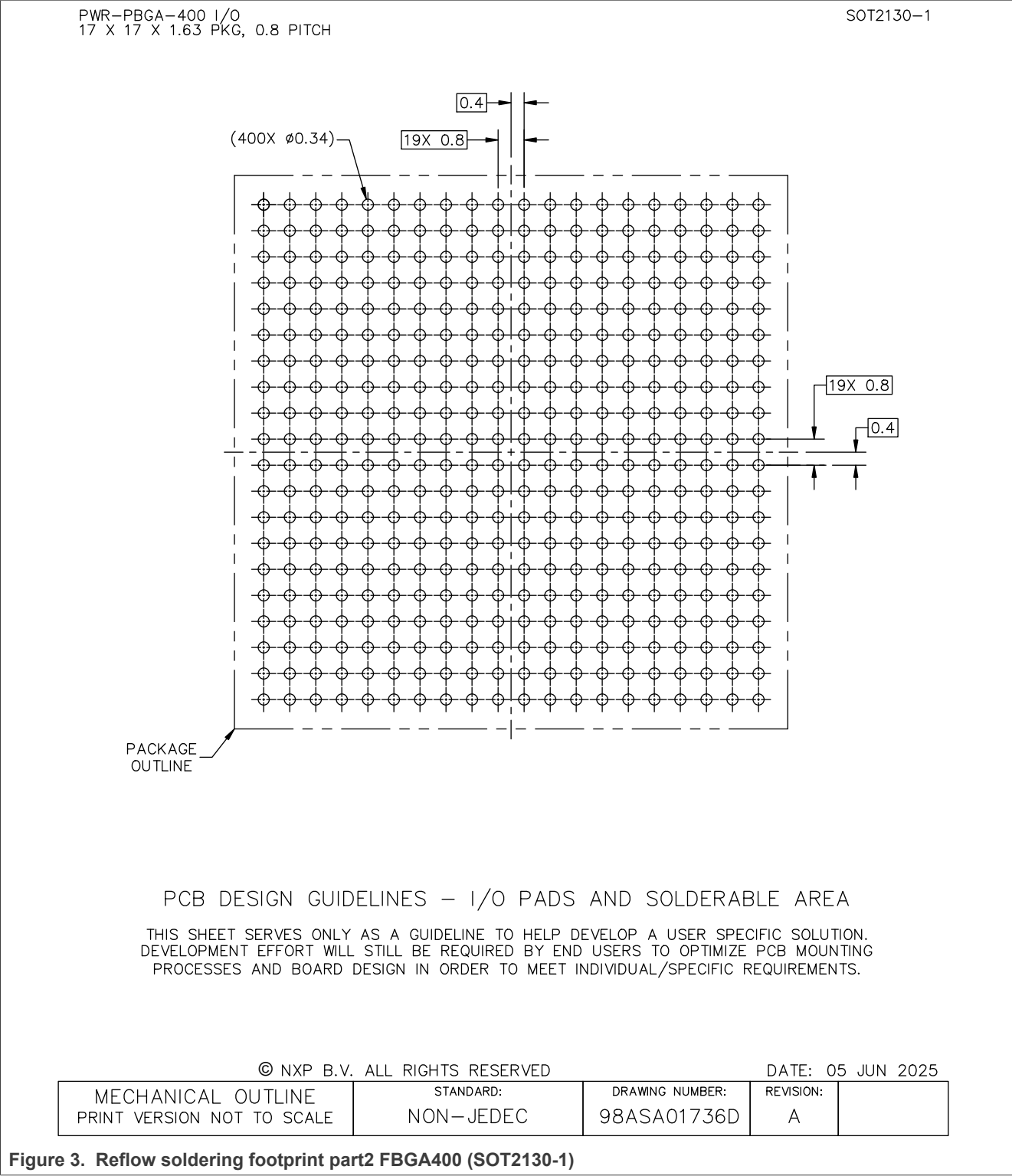


Figure 2. Reflow soldering footprint part1 FBGA400 (SOT2130-1)

LFBGA400, fine-pitch ball grid array, 400 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.63 mm body



LFBGA400, fine-pitch ball grid array, 400 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.63 mm body

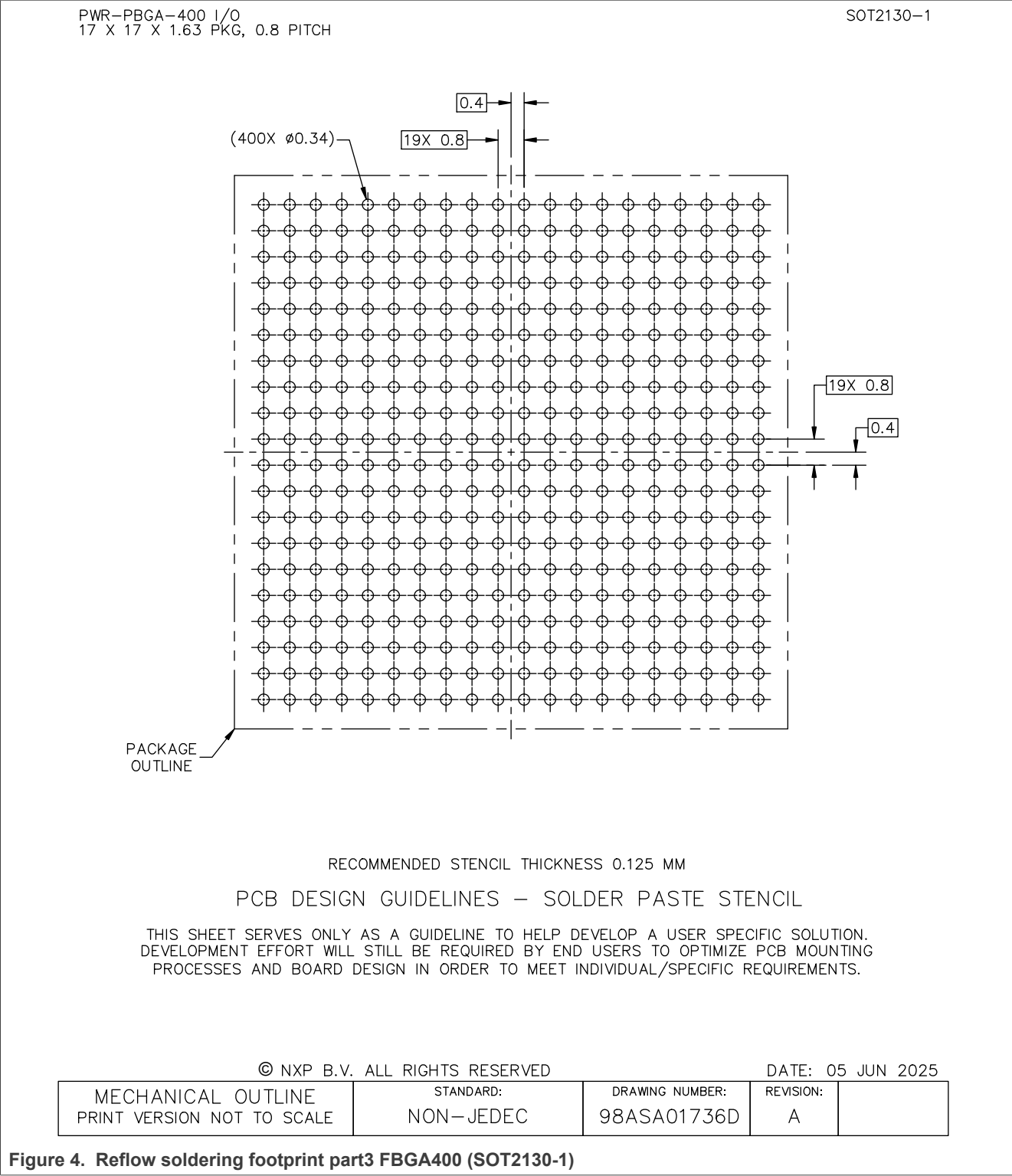


Figure 4. Reflow soldering footprint part3 FBGA400 (SOT2130-1)

LFBGA400, fine-pitch ball grid array, 400 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.63 mm body

PWR-PBGA-400 I/O  
17 X 17 X 1.63 PKG, 0.8 PITCH

SOT2130-1

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
- 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
- 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 05 JUN 2025

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01736D	REVISION: A	
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Figure 5. Package outline note FBGA400 (SOT2130-1)

## 4 Legal information

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LFBGA400, fine-pitch ball grid array, 400 terminals, 0.8 mm pitch, 17 mm x 17 mm x 1.63 mm body

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